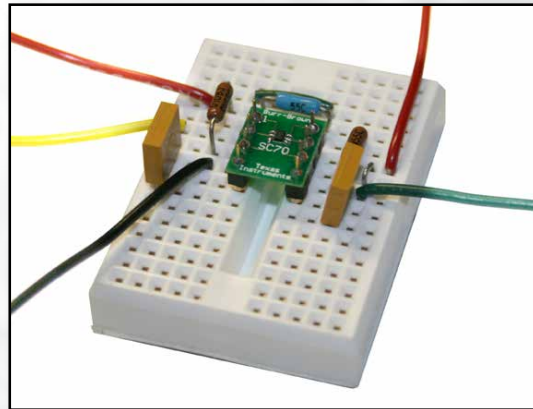


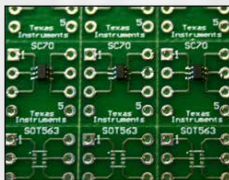
# DIP Adapter EVM

## Simplifies prototyping SMT ICs

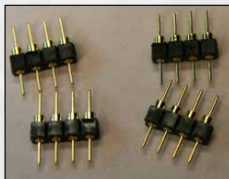
Supports SOIC-8 (U), TSSOP-8 (PW), MSOP-8 (DGK), SOT23-6 (DBV), SC70-6 (DCK) and SOT563-6 (DRL) packages



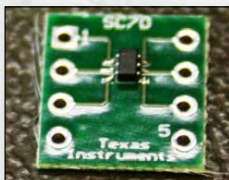
## Usage Instructions



Solder IC(s) to adapter pcb. Parts may be hand soldered or attached with IR or hot air reflow techniques.



Use long nose pliers to snap terminal strips (Samtec part number TS-132-G-AA) into 4 position lengths.



Gently flex panel at score lines to separate boards.



Insert terminal strips into a spare DIP socket to align pins.



Position board over pins and solder the connections. Carefully remove from DIP socket. Done!

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